

HRV103A

Silicon Schottky Barrier Diode for Rectifying

REJ03G0398-0100

Rev.1.00

Oct 12, 2004

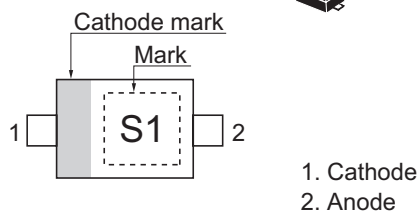
Features

- Low forward voltage drop and suitable for high efficiency rectifying.
- Thin Ultra small Resin Package (TURP) is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HRV103A	S1	TURP

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
Reverse voltage	V_R	30	V
Average rectified current	I_O^{*2}	1	A
Non-Repetitive peak forward surge current	I_{FSM}^{*1}	5	A
Junction temperature	T_J	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Notes: 1. 10ms sine wave 1 pulse

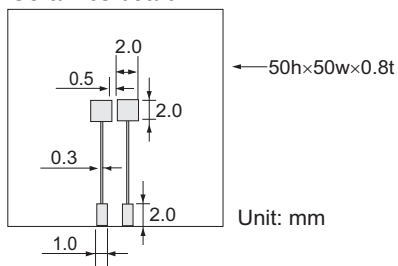
2. Ta = 44°C, With Ceramics board (board size: 50mm × 50 mm, Land size 2mm × 2 mm)
Short form wave (θ180°C), VR = 10 V.

Electrical Characteristics

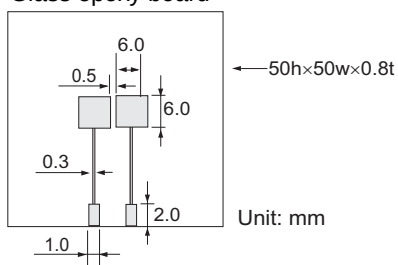
(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	—	—	0.27	V	$I_F = 100 \text{ mA}$
	V_{F2}	—	—	0.36		$I_F = 700 \text{ mA}$
	V_{F3}	—	—	0.42		$I_F = 1 \text{ A}$
Reverse current	I_{R1}	—	—	100	μA	$V_R = 5 \text{ V}$
	I_{R2}	—	—	1000		$V_R = 30 \text{ V}$
Capacitance	C	—	—	40	pF	$V_R = 10 \text{ V}$, $f = 1 \text{ MHz}$
Thermal resistance	Rth(j-a)	—	100	—	°C/W	Ceramics board ^{*1}
		—	200			Glass epoxy board ^{*2}

Notes: 1. Ceramics board



2. Glass epoxy board



3. TURP is the structure which radiates heat to a substrate, please perform mounting to a substrate by reflow.

Main Characteristics

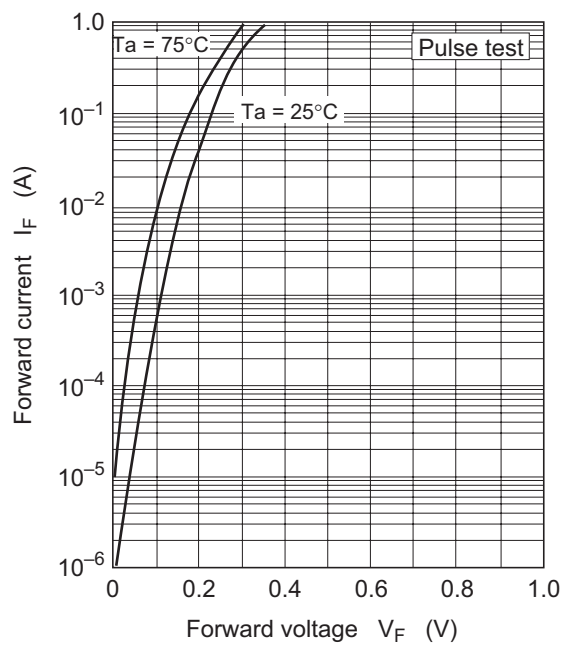


Fig.1 Forward current vs. Forward voltage

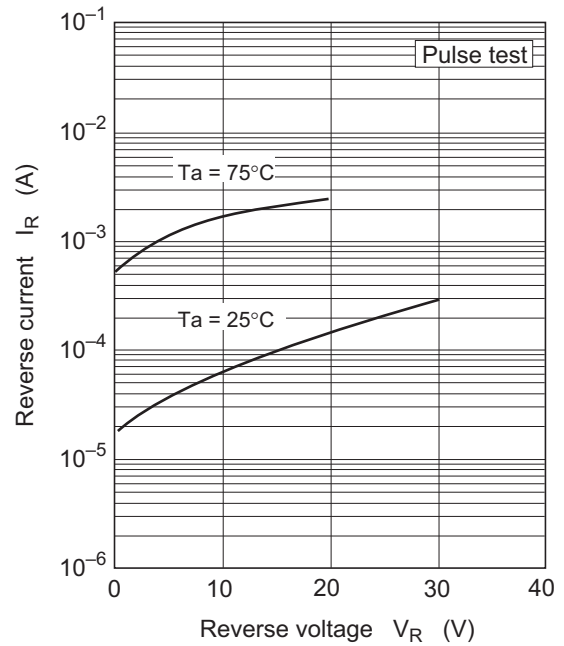


Fig.2 Reverse current vs. Reverse voltage

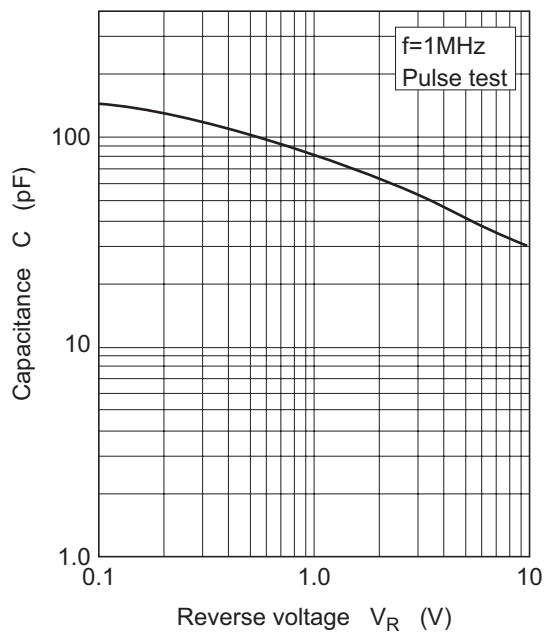


Fig.3 Capacitance vs. Reverse voltage

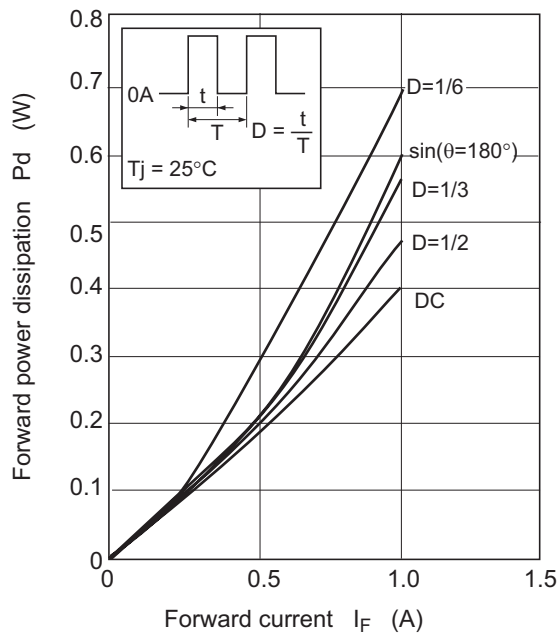


Fig.4 Forward power dissipation vs. Forward current

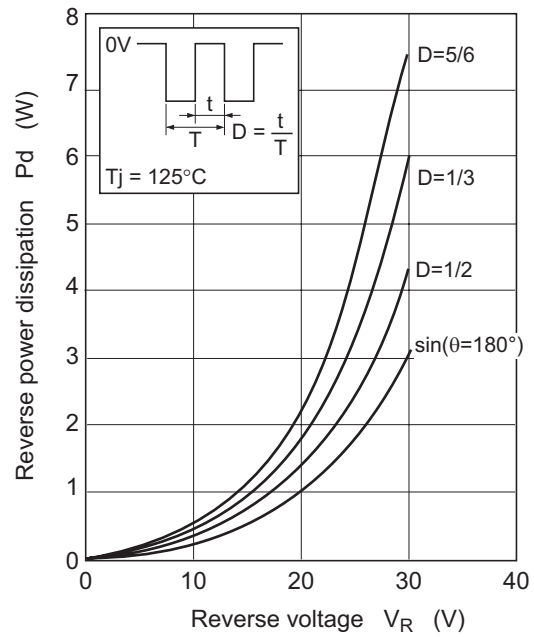


Fig.5 Reverse power dissipation vs. Reverse voltage

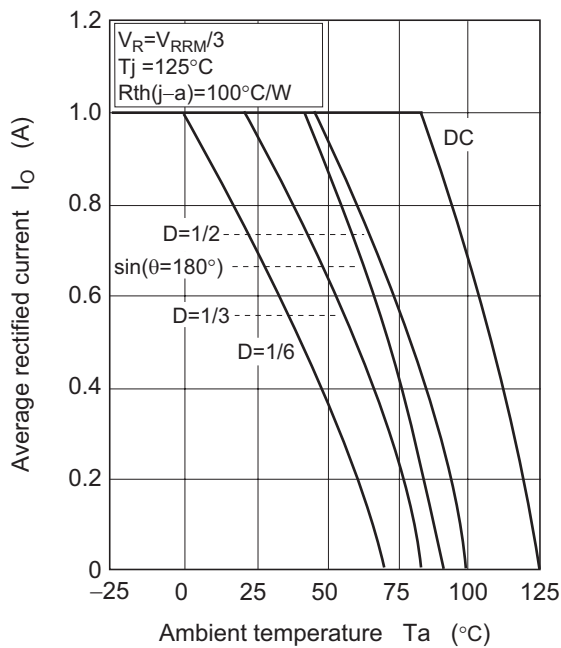
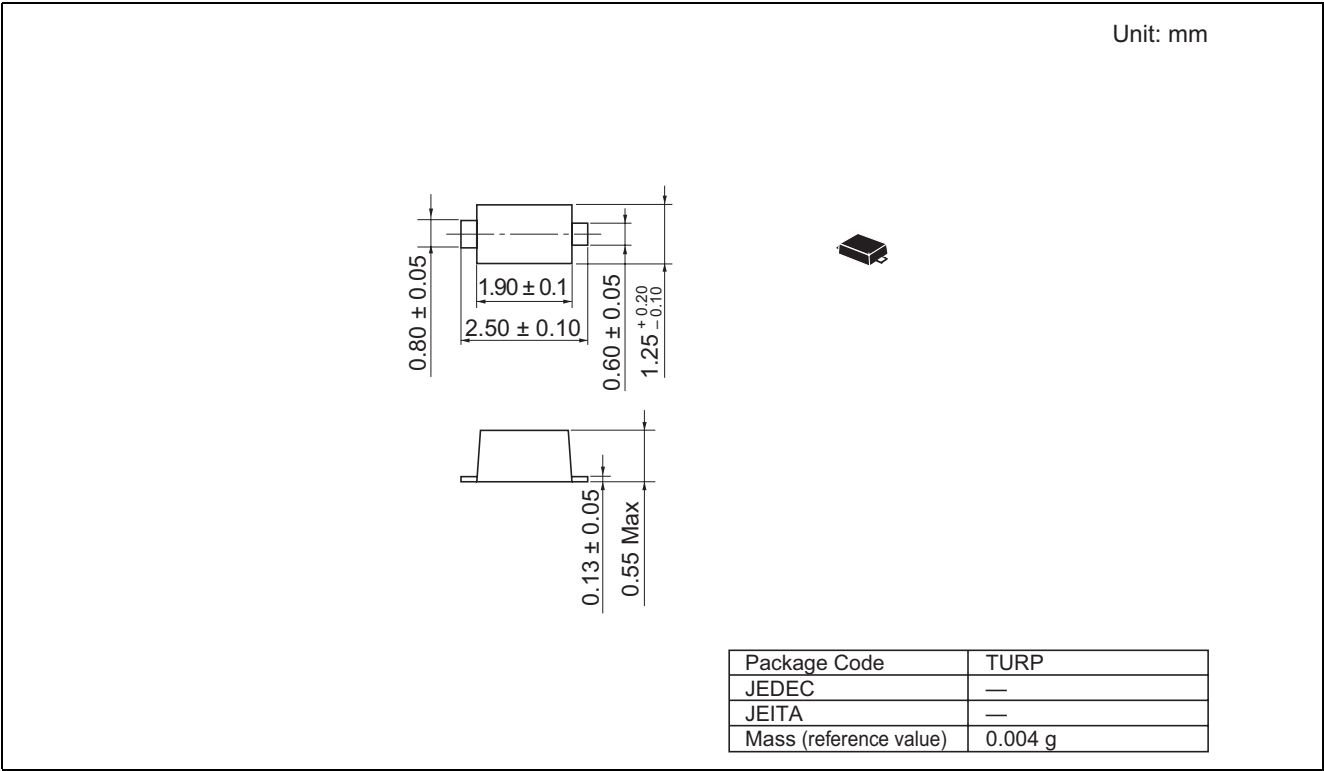


Fig.6 Average rectified current vs. Ambient temperature

Package Dimensions



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